

Dual N-Channel 20 V (D-S) MOSFET

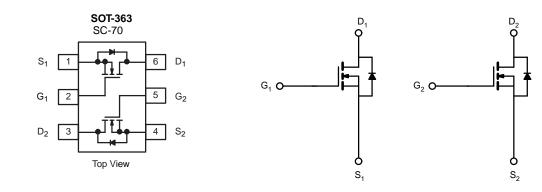
PRODUCT SUMMARY						
V _{DS} (V)	R _{DS(on)} (Ω)	I _D (A) ^a	Q _g (Typ.)			
	0.086 at V _{GS} = 4.5 V	2.6 ^a				
20	0.110 at V _{GS} = 2.5 V	2.5 ^a	5.0 nC			
	0.180 at V _{GS} = 1.8 V	2.3 ^a				

FEATURES

- Halogen-free According to IEC 61249-2-21 • Definition
- TrenchFET[®] Power MOSFET •
- 100 % R_g Tested
- Typical ESD Protection 2100 V HBM
- Compliant to RoHS Directive 2002/95/EC ٠

APPLICATIONS

· Load Switch for Portable Applications



Parameter	Symbol	Limit	Unit	
Drain-Source Voltage	V _{DS}	20	V	
Gate-Source Voltage	V _{GS}	± 12	V	
	T _C = 25 °C		2.6 ^a	
Continuous Drain Current (T. 150 °C)	T _C = 70 °C		2.2 ^a	
Continuous Drain Current ($T_J = 150 \text{ °C}$)	T _A = 25 °C	I _D	2.3 ^{a, b, c}	
	T _A = 70 °C		1.8 ^{b, c}	А
Pulsed Drain Current	I _{DM}	8		
Outline Outline Design Disate Outline	T _C = 25 °C		2.3	
Continuous Source-Drain Diode Current	T _A = 25 °C	I _S	2.10 ^{b, c}	
	T _C = 25 °C		2.70	
Maximum Dawar Dissinction	T _C = 70 °C		1.70	w
Maximum Power Dissipation	T _A = 25 °C	P _D	1.5 ^{b, c}	V
	T _A = 70 °C		1.0 ^{b, c}	
Operating Junction and Storage Temperature R	T _J , T _{stg}	- 55 to 150	°C	

THERMAL RESISTANCE RATINGS								
Parameter		Symbol	Typical	Maximum	Unit			
Maximum Junction-to-Ambient ^{b, d}	t ≤ 5 s	R _{thJA}	130	170	°C/W			
Maximum Junction-to-Foot (Drain)	Steady State R _{thJF} 80 1		100	0/11				

Notes: a. Package limited.

b. Surface mounted on 1" x 1" FR4 board.

c. t = 5 s. d. Maximum under steady state conditions is 220 °C/W. COMPLIANT

FDG6303N

Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static	•	·					
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	20			V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	J J 250.04		20		mV/°	
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I _D = 250 μA		- 2.3		- mv/°	
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = 250 \ \mu A$	0.5		2.0	V	
Gate-Source Leakage		$V_{DS} = 0 \text{ V}, V_{GS} = \pm 8 \text{ V}$			± 25	μA	
	I _{GSS}	$V_{DS} = 0 \text{ V}, \text{ V}_{GS} = \pm 4.5 \text{ V}$			1		
Zara Cata Valtaga Drain Current		$V_{DS} = 20 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$			1	μA	
Zero Gate Voltage Drain Current	IDSS	$V_{DS} = 20 \text{ V}, \text{ V}_{GS} = 0 \text{ V}, \text{ T}_{J} = 55 \text{ °C}$			10		
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \le 5 \text{ V}, \text{ V}_{GS} = 4.5 \text{ V}$	4			Α	
		$V_{GS} = 4.5 \text{ V}, I_D = 1 \text{ A}$		0.086		Ω	
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = 2.5 V, I _D = 1 A		0.110			
		V _{GS} = 1.8 V, I _D = 0.2 A		0.180		1	
Forward Transconductance ^a	9 _{fs}	V _{DS} = 4 V, I _D = 1.5 A		4		S	
Dynamic ^b	1	· · · · · · · · · · · · · · · · · · ·					
	Qg	$V_{DS} = 10 \text{ V}, \text{ V}_{GS} = 8 \text{ V}, \text{ I}_{D} = 1.5 \text{ A}$		5.0		- nC	
Total Gate Charge				3.0			
Gate-Source Charge	Q _{gs}	$V_{DS} = 10 \text{ V}, V_{GS} = 4.5 \text{ V}, I_{D} = 1.5 \text{ A}$		1.0			
Gate-Drain Charge	Q _{gd}			2.0			
Gate Resistance	R _g	f = 1 MHz	0.4	1.9	3.8	kΩ	
Turn-On Delay Time	t _{d(on)}			43	65	_	
Rise Time	t _r	V_{DD} = 10 V, R _L = 8.3 Ω		80	120		
Turn-Off Delay Time	t _{d(off)}	$I_D \cong 1.2 \text{ A}, V_{\text{GEN}} = 4.5 \text{ V}, \text{R}_g = 1 \Omega$		480	720		
Fall Time	t _f			220	330		
Turn-on Delay Time	t _{d(on)}			22	33	ns	
Rise Time	tr	$V_{DD} = 10 \text{ V}, \text{ R}_{L} = 8.3 \Omega$		46	70	-	
Turn-Off Delay Time	t _{d(off)}	$I_D \cong 1.2 \text{ A}, V_{GEN} = 8 \text{ V}, \text{ R}_g = 1 \Omega$		645	968		
Fall Time	tr			215	323		
Drain-Source Body Diode Characteristic	S	· · · · · ·					
Continuous Source-Drain Diode Current	۱ _S	T _C = 25 °C		2.6		A	
Pulse Diode Forward Current	I _{SM}	-		4			
Body Diode Voltage	V _{SD}	I _S = 1.2 A, V _{GS} = 0 V		0.8	1.2	V	
Body Diode Reverse Recovery Time	t _{rr}			9	18	ns	
Body Diode Reverse Recovery Charge	Q _{rr}			2	4	nC	
everse Recovery Fall Time t _a		I _F = 1.2 A, dl/dt = 100 A/μs, T _J = 25 °C		5			
Reverse Recovery Rise Time	t _b	1		4		ns	

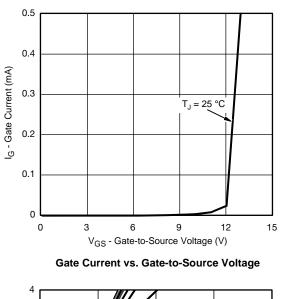
a. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %.

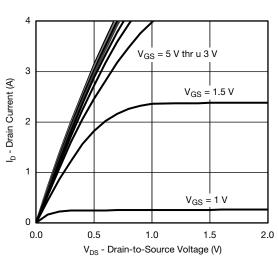
b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

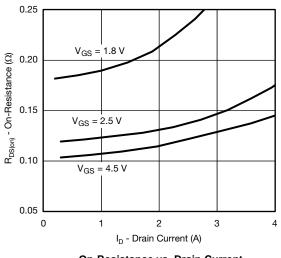
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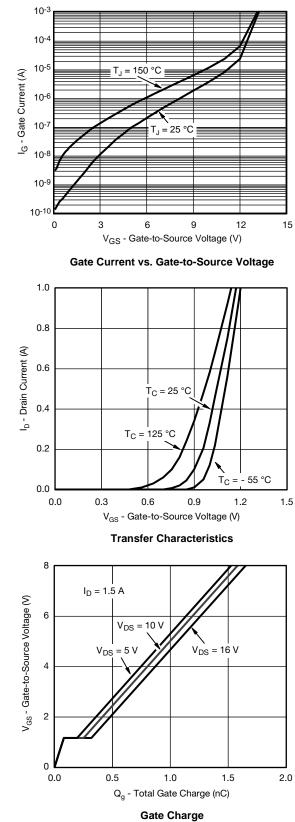




Output Characteristics

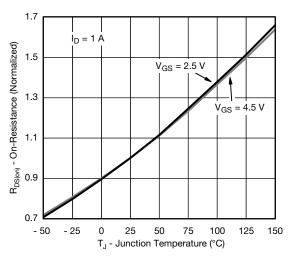


On-Resistance vs. Drain Current



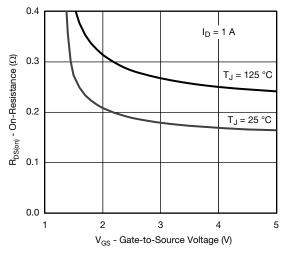
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



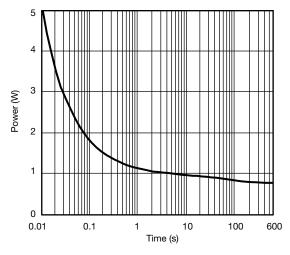


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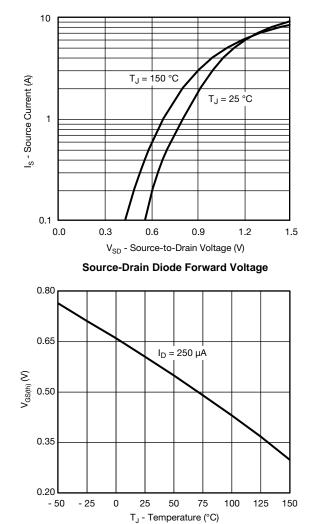




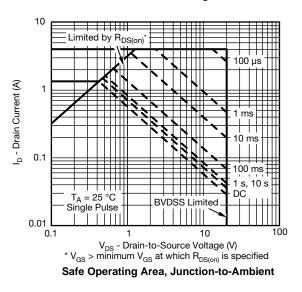
On-Resistance vs. Gate-to-Source Voltage



Single Pulse Power, Junction-to-Ambient

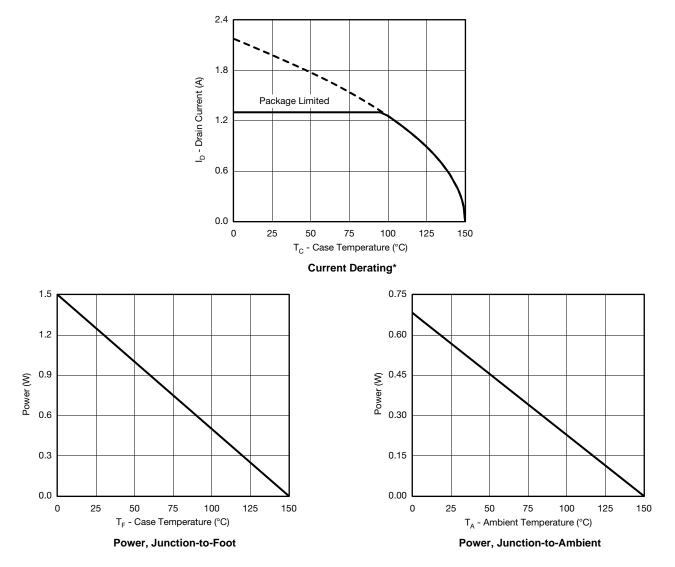


Threshold Voltage





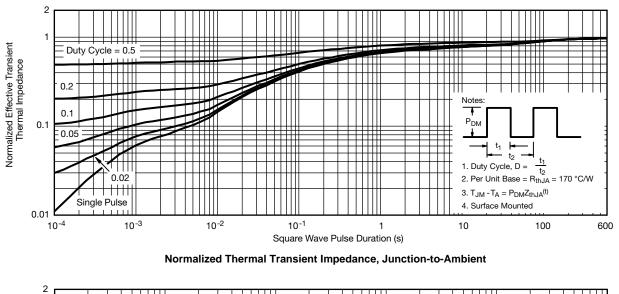
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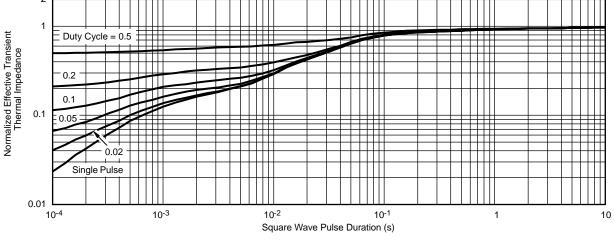


* The power dissipation P_D is based on $T_{J(max)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.



TYPICAL CHARACTERISTICS (25 C, unless otherwise noted)

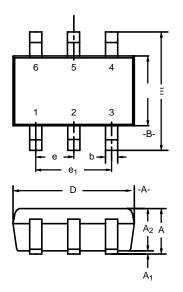


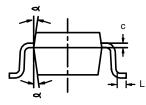


Normalized Thermal Transient Impedance, Junction-to-Foot



SC-70: 6-LEADS





	MILLIMETERS			INCHES			
Dim	Min	Nom	Max	Min	Nom	Max	
Α	0.90	-	1.10	0.035	-	0.043	
A ₁	-	-	0.10	-	-	0.004	
A ₂	0.80	-	1.00	0.031	-	0.039	
b	0.15	-	0.30	0.006	-	0.012	
С	0.10	-	0.25	0.004	-	0.010	
D	1.80	2.00	2.20	0.071	0.079	0.087	
Е	1.80	2.10	2.40	0.071	0.083	0.094	
E ₁	1.15	1.25	1.35	0.045	0.049	0.053	
е	0.65BSC			0.026BSC			
e ₁	1.20	1.30	1.40	0.047	0.051	0.055	
L	0.10	0.20	0.30	0.004	0.008	0.012	
٩	7°Nom			7°Nom			



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